

REMARKS

Favorable reconsideration of this application is respectfully requested in view of the previous amendments and the following remarks.

At the outset, appreciation is expressed to Examiner Phan for the courtesy extended to the undersigned during the April 29, 2010 interview regarding this application. The substance of the interview is reflected in the following remarks.

Before discussing the subject matter recited in the claims of this application and as a preface to commenting on the issues raised in the most recent Official Action, the following general overview is provided of features and operational characteristics associated with a method for manufacturing a USB electronic key according to at least one embodiment described and illustrated in the present application.

As discussed during the interview, an exemplary method includes cutting out, from a tape 54 having a plurality of microcircuits 56, a portion of the tape 54 including one of the microcircuits 56. Each microcircuit 56 defines USB-format contact pads and carries an electronic component connected to the pads. As also discussed during the interview, an exemplary method also includes disposing the microcircuit 56 in a bottom-half shell as illustrated in Fig. 8 or in a one-piece shell as illustrated in Fig. 10, so as to increase the thickness of the cut-out portion of the tape including the one of the microcircuits at least in the area of the contact pads of the one of the microcircuits, to have a thickness that conforms to the USB Standard. Of course, the claimed invention is not limited to the disclosed embodiments.

Turning now to the claims, Claim 15, the only independent claim currently pending after this amendment, was rejected based on the disclosures in U.S. Patent No. 6,744,634, hereinafter Yen, and U.S. Patent No. 6,159,770, hereinafter Tetaka.

Claim 15 recites a method for manufacturing a USB electronic key, including cutting out, from a tape having a plurality of microcircuits, a portion of the tape including one of the microcircuits, each microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads. Additionally, Claim 15 is amended for clarity purposes to recite increasing the thickness of the cut-out portion of the tape including the one of the microcircuits at least in the area of the contact pads of the one of the microcircuits, so as to have a thickness that conforms to the USB Standard.

The Official Action correctly notes that Yen does not disclose cutting out a portion of tape including a microcircuit from a tape having a plurality of microcircuits, but goes on to take the position that Tetaka cures this deficiency in Yen. However, as discussed during the interview, it is clear from a careful review of Tetaka's specification that Tetaka does not disclose of cutting out a portion of tape including a microcircuit from a tape having a plurality of microcircuits. For example, the process illustrated in Figs. 99A-99C of Tetaka involves separating resin packages 212 from a runner frames 234-- there is no tape at all. Additionally, the processes illustrated in Figs. 176 through 185 of Tetaka involves separating resin packages 412 or gate portions 432 from a tape. However, there is no cutting out a portion of tape including a microcircuit in any of the processes illustrated in Figs. 176 through 185. Should the Examiner continue to believe that Tetaka discloses cutting out a portion of tape including a microcircuit from a tape having a plurality of microcircuits, it is respectfully

requested that the Examiner provide a detailed explanation of the basis for this belief.

Applicants respectfully submit that amended Claim 15 is allowable over the disclosures in Yen and Tetaka for the reasons discussed above. Withdrawal of the rejection of Claim 15 is therefore respectfully requested.

The dependent claims are allowable at least by virtue of their dependence from allowable independent Claim 15. Thus, a detailed discussion of the additional distinguishing features recited in the dependent claims is not set forth at this time.

Early and favorable action with respect to this application is respectfully requested.

Should any questions arise in connection with this application or should the Examiner believe that a telephone conference with the undersigned would be helpful in resolving any remaining issues pertaining to this application, the undersigned respectfully requests that he be contacted at the number indicated below.

The Director is hereby authorized to charge any appropriate fees under 37 C.F.R. §§ 1.16, 1.17 and 1.20(d) and 1.21 that may be required by this paper, and to credit any overpayment, to Deposit Account No. 02-4800.

Respectfully submitted,

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Date: May 21, 2010

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